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June 2016

# FGB3056\_F085

# EcoSPARK® 300mJ, 560V, N-Channel Ignition IGBT

#### **Features**

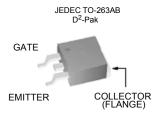
- SCIS Energy = 300mJ at T<sub>.1</sub> = 25°C
- Logic Level Gate Drive

### **Applications**

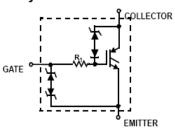
- Automotive Ignition Coil Driver Circuits
- Coil On Plug Applications



### Package



# Symbol



### Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

| Symbol               | Parameter   |                        | Ratings     | Units |
|----------------------|---|------------------------|-------------|-------|
| BV <sub>CER</sub>    | Collector to Emitter Breakdown Voltage (I <sub>C</sub> = 2mA)                   |                        | 560         | V     |
| BV <sub>ECS</sub>    | Emitter to Collector Voltage - Reverse Battery Condition (I <sub>C</sub> = -20m | 20                     | V           |       |
| E <sub>SCIS25</sub>  | $I_{SCIS}$ = 14.2A, L = 3.0mHy, $R_{GE}$ = 1K $\Omega$                          | T <sub>C</sub> = 25°C  | 300         | mJ    |
| E <sub>SCIS150</sub> | $I_{SCIS}$ = 10.8A, L = 3.0mHy, $R_{GE}$ = 1K $\Omega$                          | T <sub>C</sub> = 150°C | 170         | mJ    |
| I <sub>C25</sub>     | Collector Current Continuous, at V <sub>GE</sub> = 5V, T <sub>C</sub> = 25°C    |                        | 29          | Α     |
| I <sub>C110</sub>    | Collector Current Continuous, at V <sub>GE</sub> = 5V, T <sub>C</sub> = 110°C   | 24                     | Α           |       |
| $V_{GEM}$            | Gate to Emitter Voltage Continuous  |                        | ±10         | V     |
| D                    | Power Dissipation Total, at T <sub>C</sub> = 25°C                               | T <sub>C</sub> = 25°C  | 200         | W     |
| $P_D$                | Power Dissipation Derating, for T <sub>C</sub> > 25°C                           | T <sub>C</sub> > 25°C  | 1.33        | W/°C  |
| T <sub>J</sub>       | Operating Junction Temperature Range  |                        | -40 to +175 | °C    |
| T <sub>STG</sub>     | Storage Junction Temperature Range  |                        | -40 to +175 | °C    |
| T <sub>L</sub>       | Max. Lead Temp. for Soldering (Leads at 1.6mm from case for 10s                 | 300                    | °C          |       |
| T <sub>PKG</sub>     | Reflow soldering according to JESD020C  |                        | 260         | °C    |
| ESD                  | HBM-Electrostatic Discharge Voltage at100pF, 1500Ω                              |                        | 4           | kV    |

#### **Thermal Characteristics**

| $R_{\theta JC}$ | Thermal Resistance Junction to Case | 0.75 | °C/W |  |
|-----------------|-------------------------------------|------|------|--|
|-----------------|-------------------------------------|------|------|--|

# Electrical Characteristics of the IGBT $T_A$ = 25°C unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Тур | Max | Units |
|--------|-----------|-----------------|-----|-----|-----|-------|

#### **Off State Characteristics**

| BV <sub>CER</sub> | Collector to Emitter Breakdown Voltage | $V_{GE} = 0V, I_{CE} = 2mA,$ $R_{GE} = 1K\Omega,$ $T_{J} = -40 \text{ to } 150^{\circ}\text{C}$ |   | 530 | 560 | 600     | >        |
|-------------------|--|---|---|-----|-----|---------|----------|
| BV <sub>CES</sub> | Collector to Emitter Breakdown Voltage | $V_{GE} = 0V, I_{CE} = 10mA,$ $R_{GE} = 0\Omega,$ $T_{J} = -40 \text{ to } 150^{\circ}\text{C}$ |   | -   | 595 | -       | <b>V</b> |
| BV <sub>ECS</sub> | Emitter to Collector Breakdown Voltage | $V_{GE} = 0V, I_{CE} = -75mA,$<br>$T_{J} = 25^{\circ}C$   |   | 20  | 26  | -       | ٧        |
| BV <sub>GES</sub> | Gate to Emitter Breakdown Voltage      | I <sub>GES</sub> = ±5mA   | I <sub>GES</sub> = ±5mA                     |     | ±14 | -       | V        |
| I <sub>CER</sub>  | Collector to Emitter Leakage Current   | $V_{CE}$ = 250V, $R_{GE}$ = 1K $\Omega$   | $T_J = 25^{\circ}C$<br>$T_I = 150^{\circ}C$ | -   | -   | 40<br>1 | μA<br>mA |
| I <sub>ECS</sub>  | Emitter to Collector Leakage Current   | V <sub>EC</sub> = 20V   | $T_J = 25^{\circ}C$<br>$T_J = 150^{\circ}C$ | -   | -   | 1 40    | mA       |
| R <sub>1</sub>    | Series Gate Resistance                 |   | 1 -   | -   | 100 | -       | Ω        |

#### **On State Characteristics**

| $V_{CE(SAT)}$ | Collector to Emitter Saturation Voltage | $V_{GE}$ = 5V, $I_{CE}$ = 2A | $T_J = 25^{\circ}C$              | - | 1.0 | 1.1  | V |
|---------------|---|------------------------------|----------------------------------|---|-----|------|---|
| $V_{CE(SAT)}$ | Collector to Emitter Saturation Voltage | $V_{GE}$ = 5V, $I_{CE}$ = 8A | $T_{\rm J} = 150^{\rm o}{\rm C}$ | - | 1.3 | 1.55 | V |

# **Dynamic Characteristics**

| $Q_{G(ON)}$         | Gate Charge                       | V <sub>GE</sub> = 5V, V <sub>CE</sub> = 12V, I <sub>CE</sub> = 10A |                                 | -   | 15.6 | 20  | nC |
|---------------------|-----------------------------------|--|---------------------------------|-----|------|-----|----|
| V                   | Gate to Emitter Threshold Voltage | = 1mΛ \/ = \/  | $T_{\rm J} = 25^{\rm o}{\rm C}$ | 1.3 | 1.6  | 2.2 | V  |
| V <sub>GE(TH)</sub> | Gate to Emitter Threshold Voltage | $I_{CE}$ = 1mA, $V_{CE}$ = $V_{GE}$ ,                              | $T_{J} = 150^{\circ}C$          | -   | 1.1  |     | V  |
| $V_{GEP}$           | Gate to Emitter Plateau Voltage   | V <sub>CE</sub> = 12V, I <sub>CE</sub> = 10A                       |                                 | 1   | 2.8  | -   | V  |

### **Switching Characteristics**

| $t_{d(ON)R}$         | Current Turn-On Delay Time-Resistive  | $V_{CE}$ = 14V, $R_L$ = 1 $\Omega$ | - | 8.0  | 1.3 | μS |
|----------------------|---------------------------------------|------------------------------------|---|------|-----|----|
| $t_{rR}$             | Current Rise Time-Resistive           | $V_{GE} = 5V, R_G = 1K\Omega$      | - | 1.48 | 2.4 | μS |
| t <sub>d(OFF)L</sub> | Current Turn-Off Delay Time-Inductive | V <sub>CE</sub> = 300V, L = 1mH,   | - | 5.1  | 8.2 | μS |
| t <sub>fL</sub>      | Current Fall Time-Inductive           | $V_{GE} = 5V, R_G = 1K\Omega$      | - | 1.1  | 1.8 | μS |

# **Ordering Information**

| Device Marking | Device       | Package  | Reel Size | Tape Width | Quantity |
|----------------|--------------|----------|-----------|------------|----------|
| FGB3056        | FGB3056_F085 | TO-263AB | 330mm     | 24mm       | 800units |

# **Typical Performance Curves**

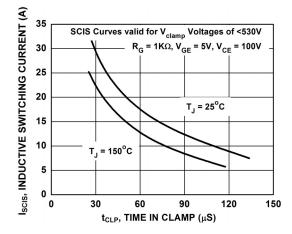


Figure 1. Self Clamped Inductive Switching Current vs. Time in Clamp

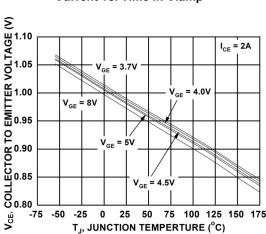


Figure 3. Collector to Emitter On-State Voltage vs. Junction Temperature

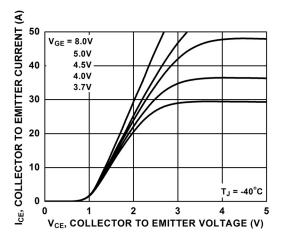


Figure 5. Collector to Emitter On-State Voltage vs. Collector Current

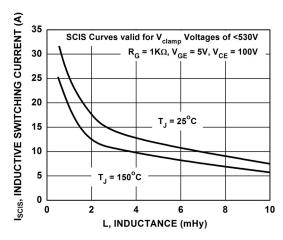


Figure 2. Self Clamped Inductive Switching Current vs. Inductance

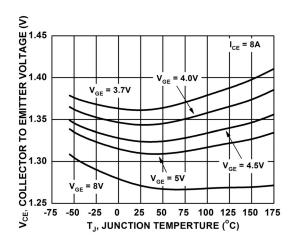


Figure 4. Collector to Emitter On-State Voltage vs. Junction Temperature

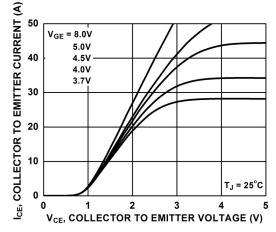


Figure 6. Collector to Emitter On-State Voltage vs. Collector Current

### Typical Performance Curves (Continued) COLLECTOR TO EMITTER CURRENT (A) 50 $V_{GE} = 8.0\dot{V}$ 5.0V 40 4.5V 4.0V 3.7V 30 20 10 $T_{\rm J} = 175^{\circ}{\rm C}$

Figure 7. Collector to Emitter On-State Voltage vs. Collector Current

V<sub>CE</sub>, COLLECTOR TO EMITTER VOLTAGE (V)

3

0

Ĝ,

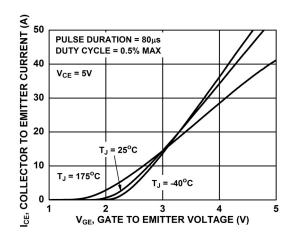


Figure 8. Transfer Characteristics

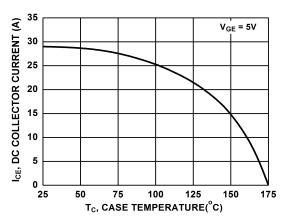


Figure 9. DC Collector Current vs. Case **Temperature** 

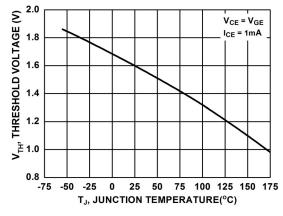


Figure 10. Threshold Voltage vs. Junction Temperature

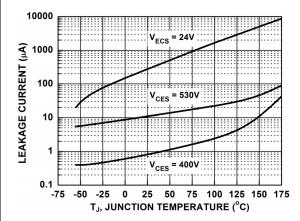


Figure 11. Leakage Current vs. Junction **Temperature** 

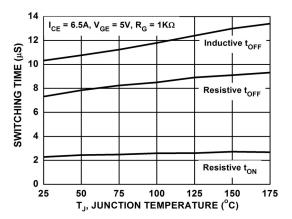
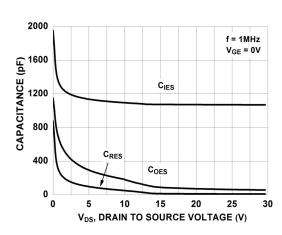


Figure 12. Switching Time vs. Junction **Temperature** 



**Typical Performance Curves** (Continued)

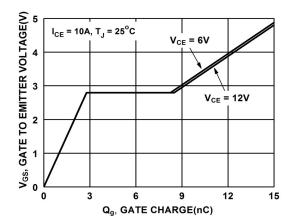


Figure 13. Capacitance vs. Collector to Emitter Voltage

Figure 14. Gate Charge

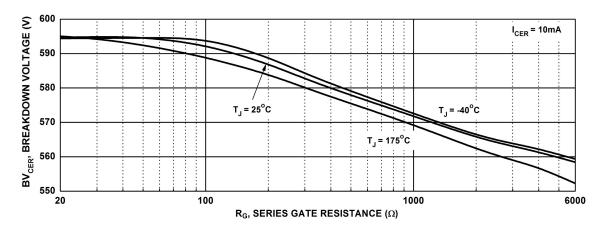


Figure 15. Break down Voltage vs. Series Gate Resistance

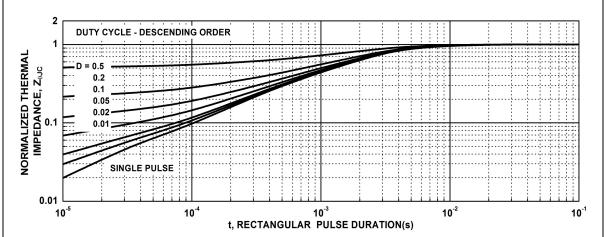


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

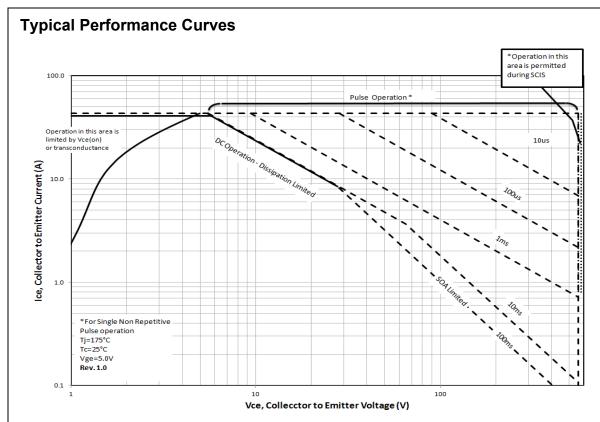
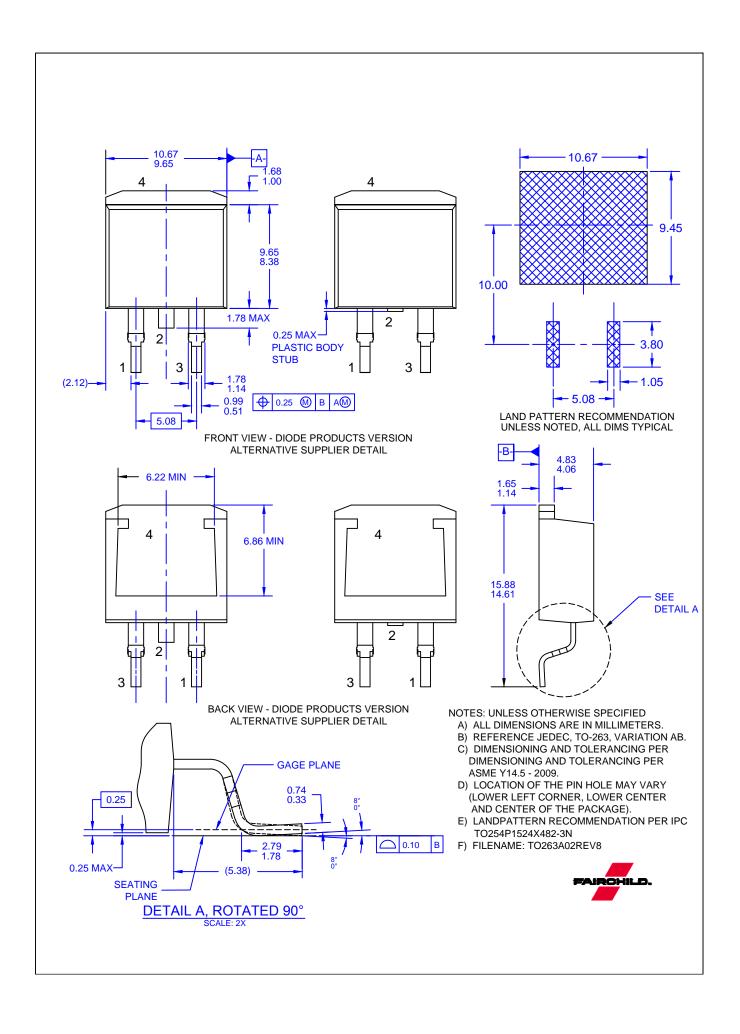


Figure 17. Forward Safe Operating Area



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